DB OR PW PACKAGE

- **Qualified for Automotive Applications**
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Meets or Exceeds Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V V_{CC} Supply
- **Operates Up To 250 kbit/s**
- **Five Drivers and Three Receivers**
- Low Standby Current . . . 1 µA Typical
- External Capacitors . . . 4 \times 0.1 μ F
- Accepts 5-V Logic Input With 3.3-V Supply
- **Always-Active Noninverting Receiver** Output (ROUT1B)
- **RS-232 Bus-Pin ESD Protection Exceeds** ±15 kV Using Human-Body Model (HBM)

(TOP VIEW) 28 C1+ C2+[GND 2 27 V+ 26 🛛 V_{CC} C2-[]3 25 C1-DOUT1 5 24 DIN1 DOUT26 23 DIN2 DOUT3 22 DIN3 21 🛛 ROUT1 RIN1⁸ RIN2 20 ROUT2 DOUT4 10 19 DIN4 RIN3 11 18 ROUT3 DOUT5 12 17 DIN5 13 FORCEON 16 ROUT1B 15 INVALID FORCEOFF 14

description/ordering information

The MAX3238 consists of five line drivers, three line receivers, and a dual charge-pump circuit with ±15-kV ESD (HBM) protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between notebook and subnotebook computer applications. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. In addition, the device includes an always-active noninverting output (ROUT1B), which allows applications using the ring indicator to transmit data while the device is powered down. These devices operate at data signaling rates up to 250 kbit/s and a maximum of $30-V/\mu s$ driver output slew rate.

ORDERING INFORMATION[†]

TA	PACKAGE		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SSOP (DB)	Tape and reel	MAX3238IDBRQ1	MAX3238Q
-40 C 10 85 C	TSSOP (PW)	Tape and reel	MAX3238IPWRQ1	MB3238Q

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

[‡]Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



description/ordering information (continued)

Flexible control options for power management are featured when the serial port and driver inputs are inactive. The auto-powerdown plus feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the device does not sense valid signal transitions on all receiver and driver inputs for approximately 30 s, the built-in charge pump and drivers are powered down, reducing the supply current to 1 µA. By disconnecting the serial port or placing the peripheral drivers off, auto-powerdown plus occurs if there is no activity in the logic levels for the driver inputs. Auto-powerdown plus can be disabled when FORCEON and FORCEOFF are high. With auto-powerdown plus enabled, the device automatically activates once a valid signal is applied to any receiver or driver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V, or has been between -0.3 V and 0.3 V for less than 30 µs. INVALID is low (invalid data) if all receiver input voltages are between -0.3 V and 0.3 V for more than 30 µs. Refer to Figure 5 for receiver input levels.

Function Tables

EACH DRIVER

		INF	PUTS	OUTPUT	
DIN	FORCEON	FORCEOFF	TIME ELAPSED SINCE LAST RIN OR DIN TRANSITION	DOUT	DRIVER STATUS
Х	Х	L	Х	Z	Powered off
L	Н	Н	Х	Н	Normal operation with
н	Н	н	Х	L	auto-powerdown plus disabled
L	L	Н	<30 s	Н	Normal operation with
н	L	н	<30 s	L	auto-powerdown plus enabled
L	L	Н	>30 s	Z	Powered off by auto-powerdown
Н	L	Н	>30 s	Z	plus feature

H = high level, L = low level, X = irrelevant, Z = high impedance

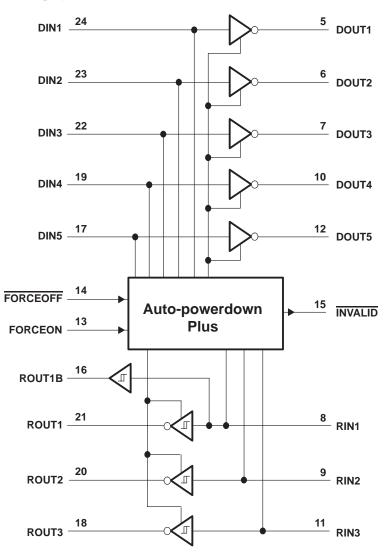
INPUTS OUTPUTS TIME ELAPSED SINCE LAST RIN **RECEIVER STATUS** RIN1 RIN2-RIN3 FORCEOFF ROUT1B ROUT **OR DIN TRANSITION** L Х L Х L Ζ Powered off while ROUT1B is active Н Х Х н Ζ L L L н <30 s L н L н н <30 s L L Normal operation with Н Н Н Н L <30 s auto-powerdown plus disabled/enabled Н Н н Н L <30 s Н >30 s Т Н Open Open

EACH RECEIVER

H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off



logic diagram (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to network GND.

- 2. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4 and Figure 6)

				MIN	NOM	MAX	UNIT
				3	3.3	3.6	
	Supply voltage		$V_{CC} = 5 V$	4.5	5	5.5	V
V Driver and a strat birth law diversity of		V _{CC} = 3.3 V	2				
۷IH	V _{IH} Driver and control high-level input voltage	DIN, FORCEOFF, FORCEON	$V_{CC} = 5 V$	2.4			V
V_{IL}	Driver and control low-level input voltage	DIN, FORCEOFF, FORCEON				0.8	V
VI	Driver and control input voltage	DIN, FORCEOFF, FORCEON		0		5.5	V
VI	Receiver input voltage			-25		25	V
TA	Operating free-air temperature		MAX3238I	-40		85	°C

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 V ± 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μF at V_CC = 5 V \pm 0.5 V.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAME	TER	TEST CONDITIONS	MIN	TYP‡	MAX	UNIT
Ц	Input leakage current	FORCEOFF, FORCEON			±0.01	±1	μΑ
		Auto-powerdown plus disabled	No load, FORCEOFF and FORCEON at V_{CC}		0.5	2	mA
ICC	Supply current	Powered off	No load, FORCEOFF at GND		1	10	
	(T _A = 25°C)	Auto-powerdown plus enabled	No load, FORCEOFF at V _{CC} , FORCEON at GND, All RIN are open or grounded		1	10	μA

[‡] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 V ± 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.



DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-a	air
temperature (unless otherwise noted) (see Note 4 and Figure 6)	

	PARAMETER	TES	ST CONDITIONS		MIN	TYP†	MAX	UNIT
VOH	High-level output voltage	All DOUT at RL = 3 k Ω to	All DOUT at $R_L = 3 k\Omega$ to GND		5	5.4		V
VOL	Low-level output voltage	All DOUT at RL = 3 k Ω to	II DOUT at $R_L = 3 k\Omega$ to GND		-5	-5.4		V
ЧΗ	High-level input current	$A^{I} = A^{CC}$				±0.01	±1	μΑ
١ _{IL}	Low-level input current	V _I at GND				±0.01	±1	μΑ
		V _{CC} = 3.6 V,	AO = 0 A			±35	±60	
IOS	IOS Short-circuit output current [‡]	V _{CC} = 5.5 V,	AO = 0 A			±40	±100	mA
r _o	Output resistance	V _{CC} , V+, and V– = 0 V,	$V_{O} = \pm 2 V$		300	10M		Ω
loff	Output leakage current	FORCEOFF = GND,	$V_{O} = \pm 12 V$,	$V_{CC} = 0$ to 5.5 V			±25	μΑ

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

[‡] Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 V \pm 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μF at V_{CC} = 5 V \pm 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
	Maximum data rate	C _L = 1000 pF, One DOUT switching,	R _L = 3 kΩ, See Figure 1	150	250		kbit/s
^t sk(p)	Pulse skew§	C _L = 150 pF to 2500 pF	$R_L = 3 k\Omega$ to 7 kΩ, See Figure 2		100		ns
SR(tr)	Slew rate, transition region	V _{CC} = 3.3 V,	C _L = 150 pF to 1000 pF	6		30	V/us
(see Figure 1)	(see Figure 1)	$R_L = 3 k\Omega$ to 7 k Ω	C _L = 150 pF to 2500 pF	4		30	v/µS

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

 $Pulse skew is defined as |t_{PLH} - t_{PHL}|$ of each channel of the same device.

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 V \pm 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.



RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4 and Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Vон	High-level output voltage	I _{OH} = -1 mA	V _{CC} – 0.6 V	V _{CC} – 0.1 V		V
VOL	Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
×	Desitive sais signation to be added to the set	V _{CC} = 3.3 V		1.5	2.4	V
VIT+	Positive-going input threshold voltage	$V_{CC} = 5 V$		1.8	2.4	V
	Manual theory and the state of the state of the state of the state	V _{CC} = 3.3 V	0.6	1.2		
V _{IT} –	Negative-going input threshold voltage	$V_{CC} = 5 V$	0.8	1.5		V
V _{hys}	Input hysteresis (V _{IT+} – V _{IT} _)			0.3		V
loff	Output leakage current (except ROUT1B)	FORCEOFF = 0 V		±0.05	±10	μA
ri	Input resistance	$V_I = \pm 3 V \text{ to } \pm 25 V$	3	5	7	kΩ

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 V ± 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Note 4)

PARAMETER		TEST CONDITIONS	ΜΙΝ ΤΥΡ [†] ΜΑΧ	UNIT
^t PLH	Propagation delay time, low- to high-level output		150	ns
^t PHL	Propagation delay time, high- to low-level output	C _L = 150 pF, See Figure 3	150	ns
t _{en}	Output enable time		200	ns
^t dis	Output disable time	$C_L = 150 \text{ pF}, R_L = 3 \text{ k}\Omega$, See Figure 4	200	ns
^t sk(p)	Pulse skew [‡]	See Figure 3	50	ns

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

[‡]Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

NOTE 4: Testing supply conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.15 V; C1–C4 = 0.22 μ F at V_{CC} = 3.3 V \pm 0.3 V; and C1 = 0.047 μ F and C2–C4 = 0.33 μF at V_{CC} = 5 V \pm 0.5 V.



AUTO-POWERDOWN PLUS SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
VT+(valid)	Re <u>ceiver in</u> put threshold for INVALID high-level output voltage	$\frac{\text{FORCEON}}{\text{FORCEOFF}} = \text{GND},$			2.7	V
V _{T-(valid)}	Receiver input threshold for INVALID high-level output voltage	$\frac{\text{FORCEON}}{\text{FORCEOFF}} = \text{ORD},$	-2.7			V
VT(invalid)	Receiver input threshold for INVALID low-level output voltage	$\frac{\text{FORCEON} = \text{GND},}{\text{FORCEOFF} = \text{V}_{CC}}$	-0.3		0.3	V
VOH	INVALID high-level output voltage	$I_{OH} = -1 \text{ mA}$, FORCEON = GND, FORCEOFF = V _{CC}	V _{CC} – 0.6			V
VOL	INVALID low-level output voltage	$I_{OL} = 1.6 \text{ mA}$, FORCEON = GND, FORCEOFF = V _{CC}			0.4	V

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

PARAMETER	MIN	TYP†	MAX	UNIT
Propagation delay time, low- to high-level output		0.1		μs
Propagation delay time, high- to low-level output		50		μs
Supply enable time		25		μs
Receiver or driver edge to auto-powerdown plus	15	30	60	S
	Propagation delay time, low- to high-level output Propagation delay time, high- to low-level output Supply enable time	Propagation delay time, low- to high-level output Propagation delay time, high- to low-level output Supply enable time	Propagation delay time, low- to high-level output 0.1 Propagation delay time, high- to low-level output 50 Supply enable time 25	Propagation delay time, low- to high-level output 0.1 Propagation delay time, high- to low-level output 50 Supply enable time 25

[†] All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION

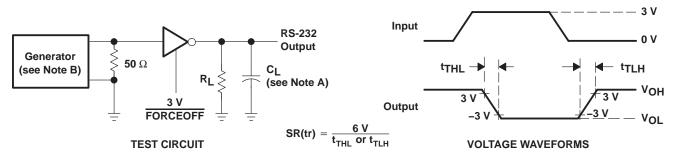
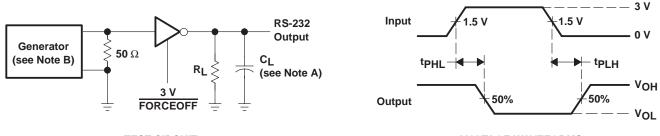




Figure 1. Driver Slew Rate



PARAMETER MEASUREMENT INFORMATION



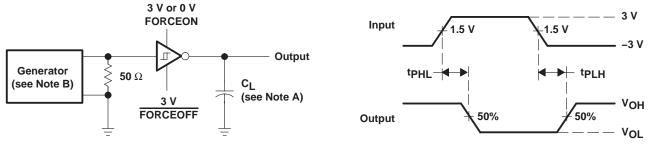
TEST CIRCUIT

VOLTAGE WAVEFORMS

NOTES: A. CI includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 250 kbit/s, Z_{O} = 50 Ω , 50% duty cycle, $t_{r} \le 10$ ns, $t_{f} \le 10$ ns.

Figure 2. Driver Pulse Skew

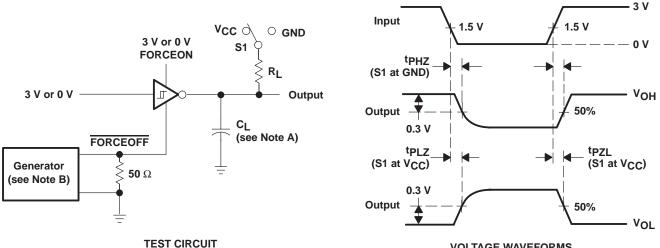


TEST CIRCUIT

VOLTAGE WAVEFORMS

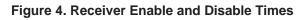
- NOTES: A. CL includes probe and jig capacitance.
 - B. The pulse generator has the following characteristics: $Z_0 = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns, $t_f \le 10$ ns.

Figure 3. Receiver Propagation Delay Times



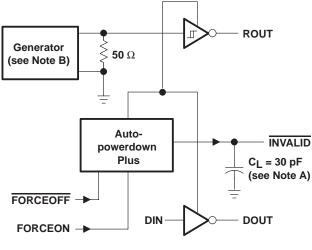
VOLTAGE WAVEFORMS

- NOTES: A. $C_{\mbox{L}}$ includes probe and jig capacitance.
 - B. The pulse generator has the following characteristics: $Z_0 = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns, $t_f \le 10$ ns.
 - C. tPLZ and tPHZ are the same as tdis.
 - D. t_{PZL} and t_{PZH} are the same as t_{en} .

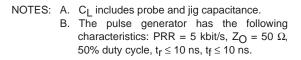


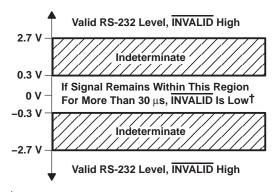


PARAMETER MEASUREMENT INFORMATION

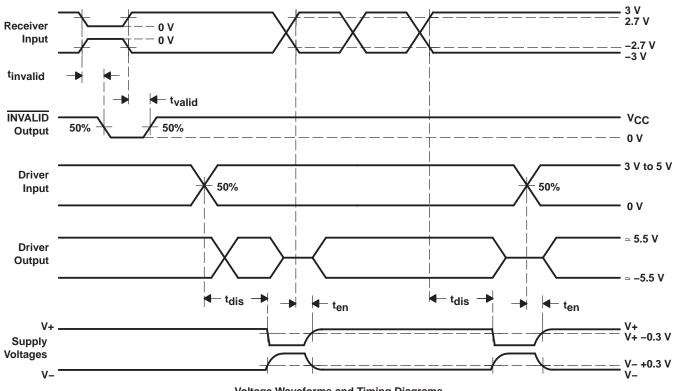


TEST CIRCUIT





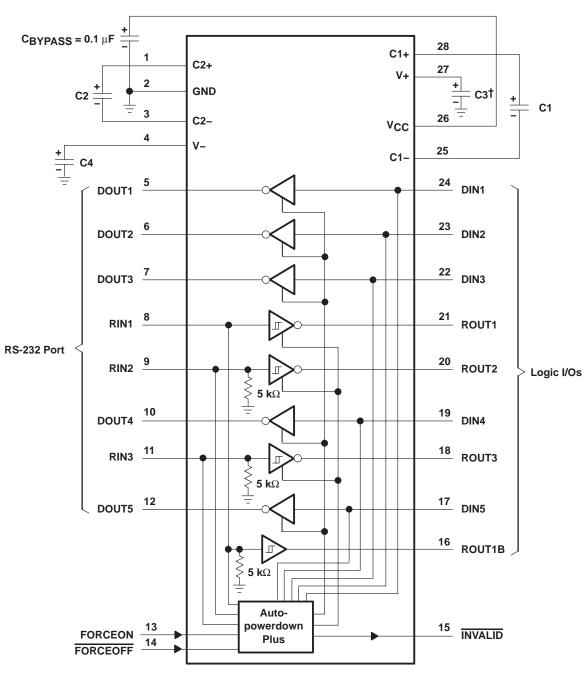
[†]Auto-powerdown plus disables drivers and reduces supply current to 1 µA.



Voltage Waveforms and Timing Diagrams

Figure 5. INVALID Propagation-Delay Times and Supply-Enabling Time





APPLICATION INFORMATION

 $^{\dagger}\,\text{C3}$ can be connected to V_CC or GND. NOTE A: Resistor values shown are nominal.

V_{CC} vs CAPACITOR VALUES

V _{CC}	C1	C2, C3, and C4			
$\begin{array}{c} 3.3 \ V \pm 0.15 \ V \\ 3.3 \ V \pm 0.3 \ V \\ 5 \ V \pm 0.5 \ V \\ 3 \ V \ to \ 5.5 \ V \end{array}$	0.1 μF 0.22 μF 0.047 μF 0.22 μF	0.1 μF 0.22 μF 0.33 μF 1 μF			

Figure 6. Typical Operating Circuit and Capacitor Values





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
MAX3238IPWQ1	ACTIVE	TSSOP	PW	28	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB3238Q	Samples
MAX3238IPWRG4Q1	ACTIVE	TSSOP	PW	28	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB3238Q	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

OTHER QUALIFIED VERSIONS OF MAX3238-Q1 :

• Catalog : MAX3238

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

TEXAS INSTRUMENTS

www.ti.com

7-Apr-2024

TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)	
MAX3238IPWQ1	PW	TSSOP	28	50	530	10.2	3600	3.5	

PW (R-PDSO-G28)

PLASTIC SMALL OUTLINE



All finited dimensions die in finite cers. Dimensioning e
 B. This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153



LAND PATTERN DATA



NOTES: All linear dimensions are in millimeters. Α.

- B. This drawing is subject to change without notice.
 C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.

E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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